



Ampoc Far East Co., Ltd

揚博科技股份有限公司
Ampoc Far-East Co., Ltd

股票代號：2493



2020/09/17



1. Ampoc Profile
2. Company History
3. Products Introduction and Applications
4. Financial Information
5. Future Outlook





Ampoc Far East Co., Ltd

1. Company Profile

Company : AMPOC Far-East Co., Ltd.

**Address : 17F., No.171, Sung-Teh Road,
Taipei, Taiwan**

Tel : (02) 2726-2220

Fax : (02) 2726-2227

E-mail : 1service@ampoc.com.tw

Responsible Person :

Chairman & C.E.O., Mr. Ronald S. Su

President, Mr. Alden Chiao

Since : November 1, 1980

Paid-up Capital : NT\$ 1,144 Million

Employee : 280 people



*Chairman & C.E.O.,
Mr. Ronald S. Su*



2. Company History

AMPOC's History



2019/01

- Ampec invested in Ampec Trading (Shanghai) Co., Ltd through the subsidiary in Hong Kong.

2006/12

- Ampec merged Yang Shin Investment Co., Ltd which Ampec owned 100%.

2002/01

- Ampec was approved to list on the Taiwan Stock Exchange, Stock Code: 2493.

2001/06

- Stock dividend was issued, resulting in total capital of NT\$905 million.

2000/10

- Paid-in capital was increased to NT\$73.7 million.

1999/12

- Ampec merged with TTCM and issued additional 21,107,000 shares, paid-in capital increased to NT\$57.1 million.

1998/12

- Ampec was approved as public company.
Ampec was engaged in capitalization of NT\$10.2 million, paid-in capital increased to NT\$30 million.

1998/03

- Ampec established the inspection lab. with precision instruments to enhance our service quality.

1997/03

- Ampec purchased the office which located at 17F, No.171, Sung-Teh Rd., Sinyi District, Taipei.

1987/05

- TCM in Japan which was a master manufacturer of PCB Wet Process established TTCM in CHUNG-LI industrial zone, Taiwan. Ampec invested in TTCM and obtained the sole global distribution agreement except in Japan.

1980/11

- Ampec was founded in Taipei with initially registered capital of NT\$1 million.



3. Products Introduction and Applications

- Products Introduction
 - Ampoc Wing Vertical System
 - Laser Heater TC Bonder
- Applications
 - Semiconductor (Front-end)
 - Advanced PKG
 - 5G/AI



Ampoc Far East Co., Ltd



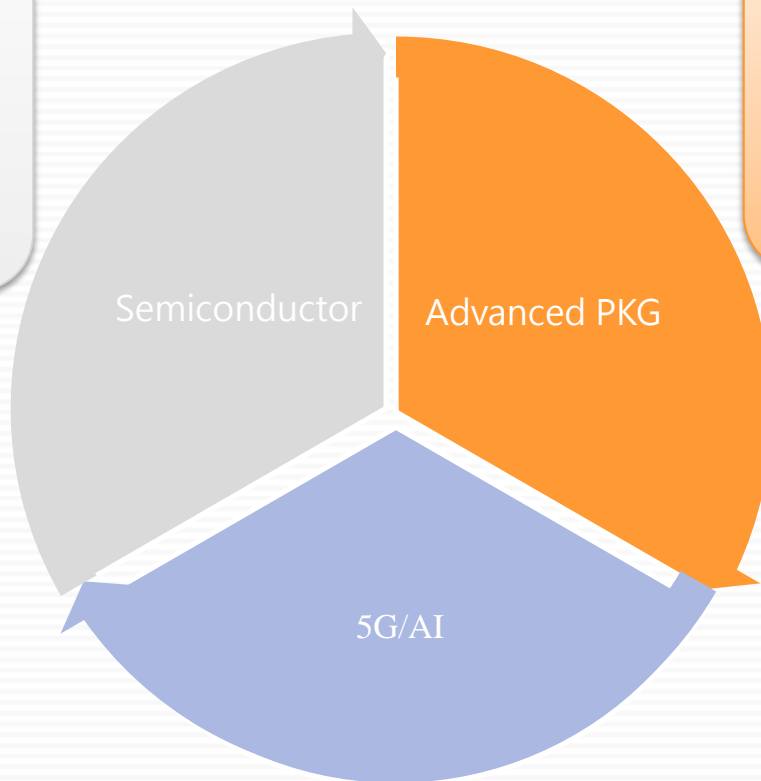
Applications





Applications - core strategy for development

- ✓ Solder bump plating chemicals
- ✓ 3D-IC · FOWLP high-speed plating chemicals
- ✓ UBM high-selective etching chemicals
- ✓ High-resolution PR
- ✓ Hard Mask

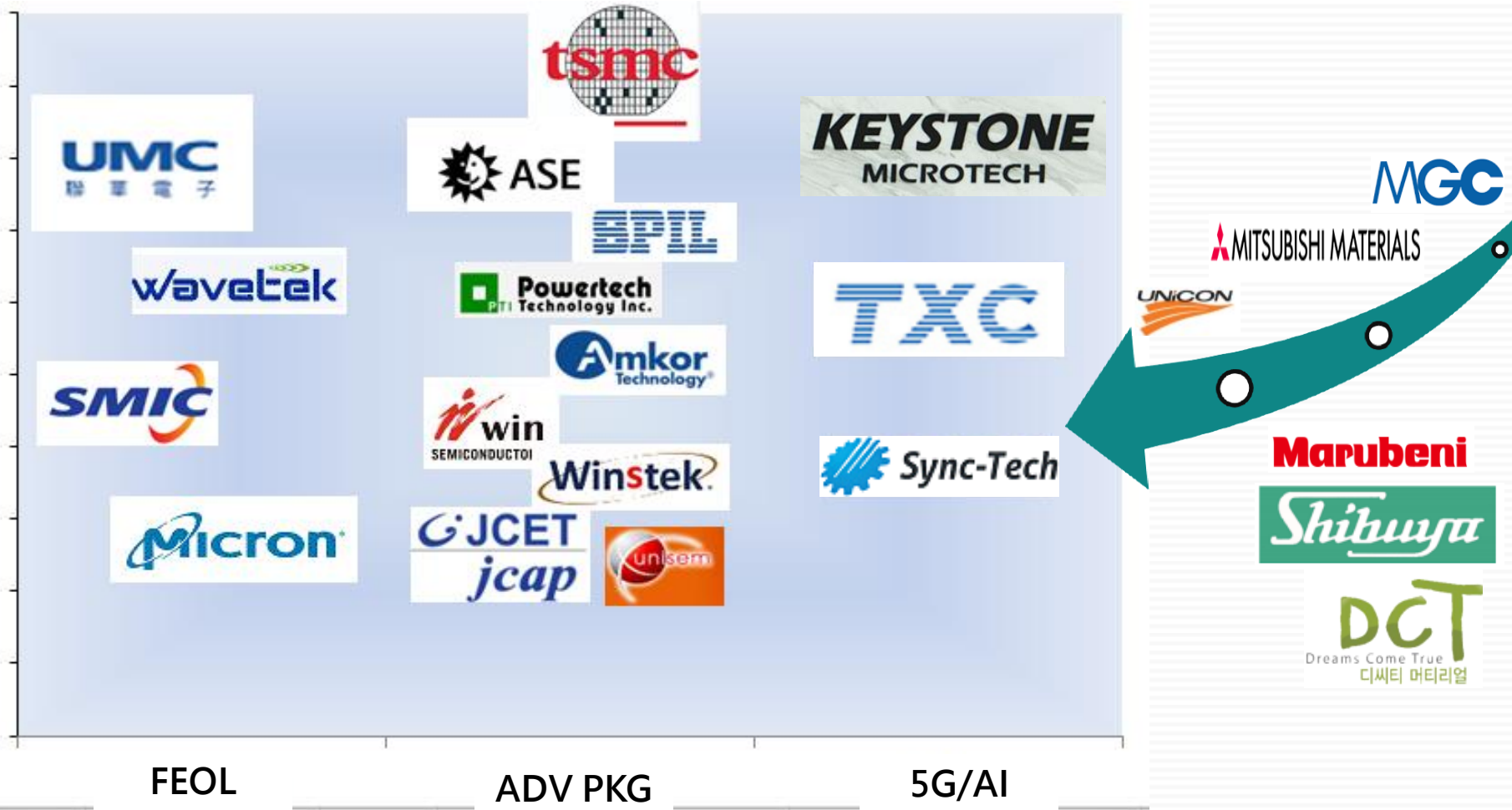


- ✓ Chemicals for lead frame metal finish
- ✓ EDPR for QFN lead frame & crystal oscillator

- ✓ AiP (Antenna in Package) testing device
- ✓ MLO probe card for 5G chip testing

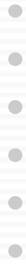


Customers & Partners





Ampoc Far East Co., Ltd

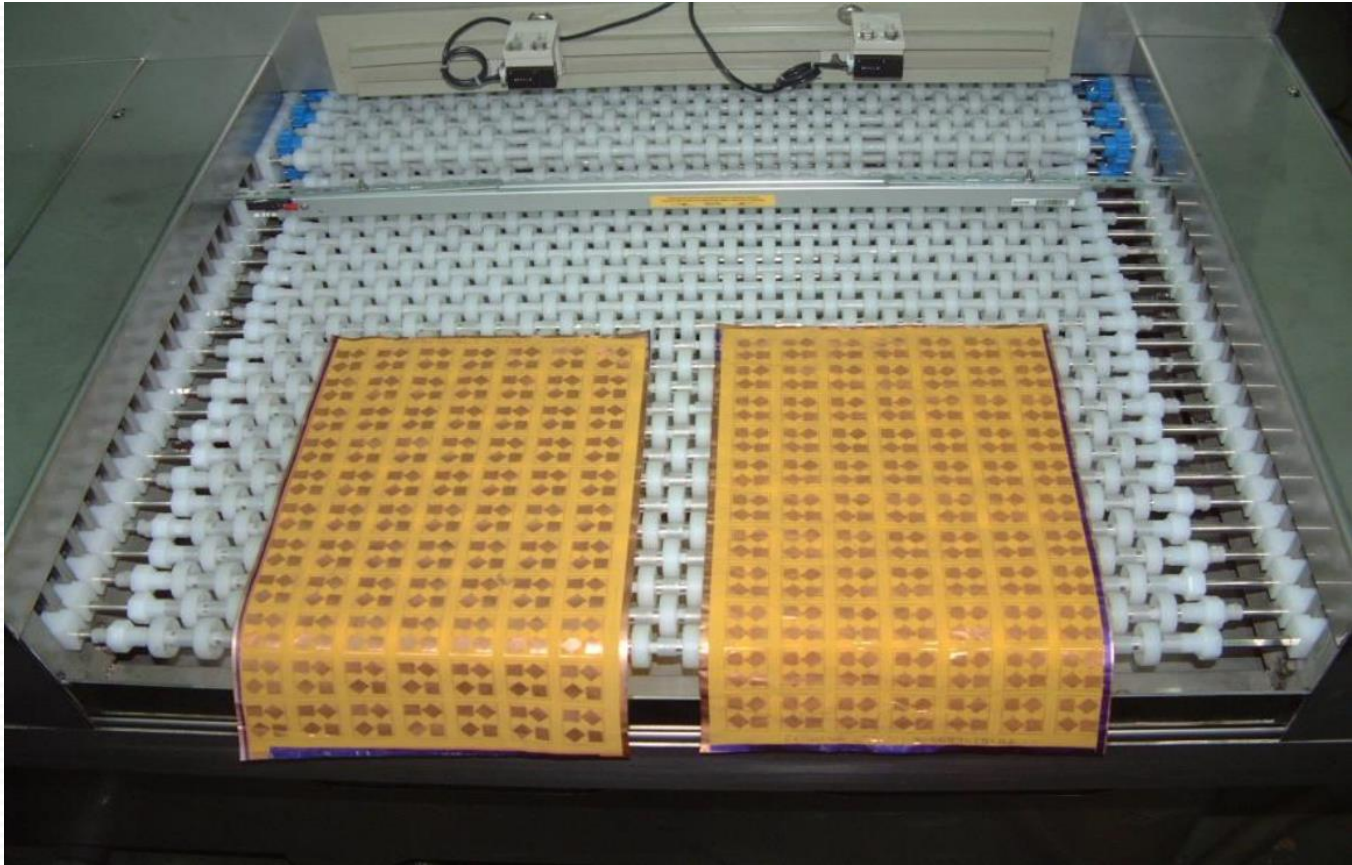


4. Products Introduction





Conventional horizontal System

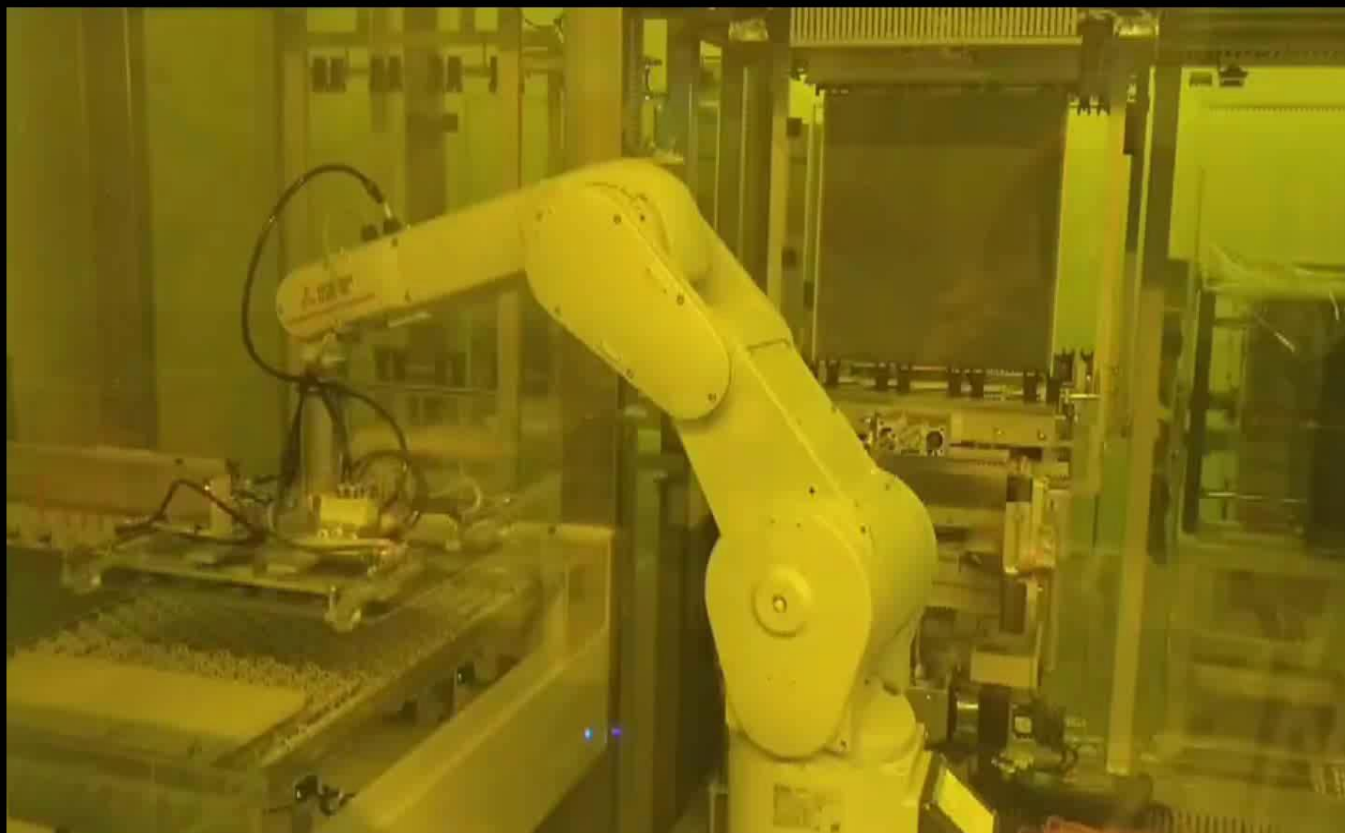




Ampoc Far East Co., Ltd

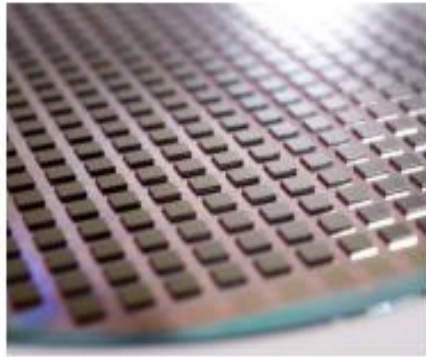
ABF Ampoc Wing Vertical System

Ampoc Wing生產ABF載板實況





Laser Heater TC Bonder



- Fast heating and cooling
- Low thermal expansion
- Localized heating





Market trends & forecast in 2020

Global portable device and equipment markets were suffering great impact due to COVID-19 hit in 1H 2020. It was the main factor of production suspension, labor shortage, supply chain disruption, caused serious damages on every production lines, and paused the growth of hi-tech industry unexpectedly. In addition, the dramatic trade war between US and China, post-pandemic world market, power shuffle after US presidential election, all uncertainties can bring challenges to the world market in 2H as well.

With many years of experience and outstanding integration of upstream and downstream supply chain in electronic industry, Taiwan is the market which is blessed with several advantages. AMPOC is the total solution provider which owns prudential management team. It is the company which considers market position and actively offers solutions for FEOL, ADV PKG, and 5G/AI applications to customers.



Taiwan PCB industry review & and outlook 2020

- 2020 market share of PCB industry (by country):
- Taiwan : 31.4% **=** (31.3%)
- China : 26.5% **↑** (23.0%)
- Japan : 17.3% **↓** (19.1%)

Although Taiwan tops global market with 31.4% market share in 2019, China reaches 26.5% and is the only one with 13.2% market growth rate. The key is from the growth of 5G network facilities demand.

- Demands for IC substrate, mobile PCB, blue tooth devices are supporting the market growth.
- In 2020 2H, production capacities for products such as 5G boards, FPCB, Rigid-Flex PCB are to increase, and the applications are smart phone, automobile, IoT and network communication products.
- Equipment demands outlook in 2020 :
 - Advanced ABF substrate
 - High-end products including 5G, SLP, HDI, FPCB
 - Electric Vehicle & safety devices



5. Financial Information

Condensed Statement of Comprehensive Income from 2018 to 2020 H1

Unit: NT\$ thousands (Except EPS: NT\$)

| Item | Year | 2018 | 2019 (consolidated) | 2020 H1 (consolidated) |
|----------------------|------|-----------|------------------------|---------------------------|
| Net Revenue | | 2,400,520 | 2,482,446 | 1,269,663 |
| Gross profit | | 765,833 | 653,556 | 332,029 |
| Gross margin(%) | | 31.90 | 26.33 | 26.15 |
| Operating income | | 423,229 | 354,944 | 193,177 |
| Net income after tax | | 342,985 | 228,519 | 193,021 |
| EPS | | 3.00 | 2.00 | 1.69 |



Condensed Balance Sheet from 2018 to 2020 H1

Unit: NT\$ thousands (Except EPS: NT\$)

| Item | Year | 2018 | 2019 (consolidated) | 2020 H1 (consolidated) |
|--------------------------------|------|------------------|------------------------|---------------------------|
| Current Assets | | 2,713,049 | 2,660,223 | 2,929,904 |
| Non-current Assets | | 758,096 | 708,293 | 741,272 |
| Total Assets | | 3,471,145 | 3,368,516 | 3,671,176 |
| Current Liabilities | | 938,712 | 892,531 | 1,287,065 |
| Non-current Liabilities | | 108,930 | 126,181 | 128,635 |
| Total Liabilities | | 1,047,642 | 1,018,712 | 1,415,700 |



Financial Analysis from 2018 to 2020 H1

| Item | Year | 2018 | 2019 (consolidated) | 2020 H1 (consolidated) |
|---|------|---------------|------------------------|---------------------------|
| Debts Ratio (%) | | 30.18 | 30.24 | 38.56 |
| Current Ratio(%) | | 289.02 | 298.05 | 227.64 |
| Average Inventory Turnover (Times) | | 1.89 | 2.19 | 2.12 |
| Return on Equity (%) | | 14.66 | 9.57 | 8.38 |



Future outlook

- Business development direction
- Competitive Advantage

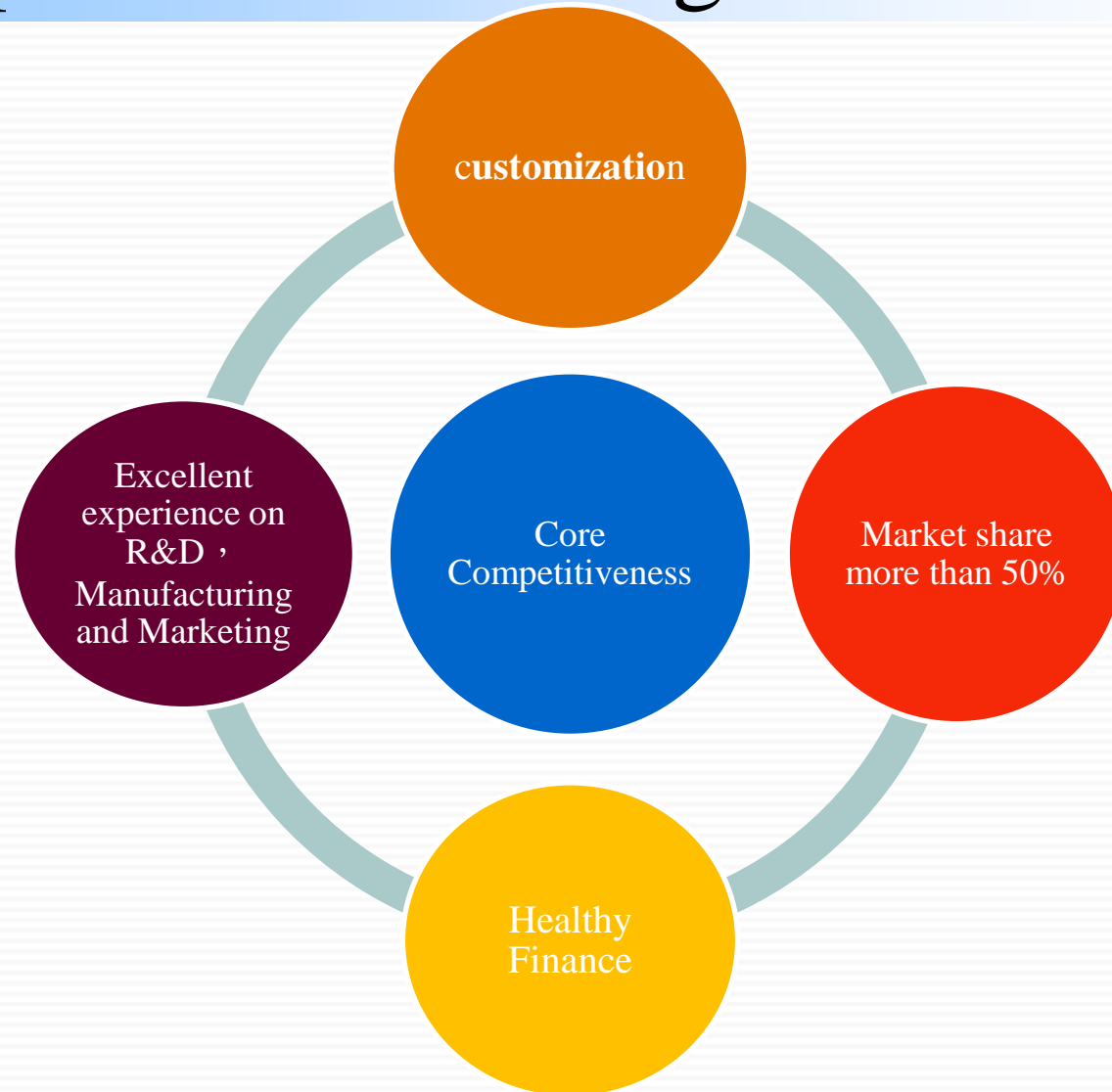


Business development direction

- Developing innovative technology equipment
 - 5G application substrate
 - FPCB and RPCB
 - Automotive HDI substrate
 - Smart equipment
- Developing new market
 - Southeast Asia
 - India

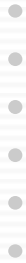


Competitive Advantage





Ampoc Far East Co., Ltd



Thank you

The End

